



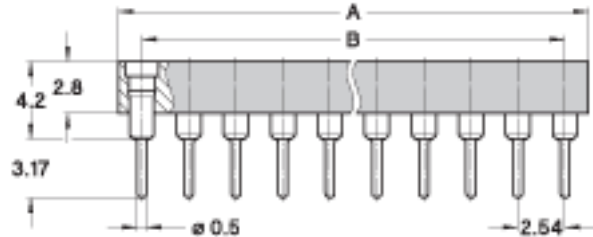
preci-dip

PGA / BGA / PLCC SOCKETS

SERIES
510

510-PP-NNN-XX-XXX101
PGA
Solder tail

Pin grid array sockets, standard solder version.



TECHNICAL SPECS.:

| | |
|----------------------------|---|
| Insulator | Black glass filled polyester PCT-GF30-FR |
| Flammability | UL 94V-O |
| Sleeve | Brass CuZn36Pb3 (C36000) |
| Contact | Clip (6 finger): Beryllium copper (C17200) |
| Accepted pin Ø | 0.40 to 0.56 mm |
| Insertion force | 0.7 N typ. |
| Withdrawal force | 0.4 N typ. (polished steel gauge Ø 0.46 mm) |
| Mechanical life | Min. 100 cycles |
| Rated current | 1 A |
| Contact resistance | Max. 10 m |
| Dielectric strength | Min. 1000 V RMS |

ORDERING INFORMATION:

| | | |
|-----------------|--------|--------------|
| PP Plating code | Sleeve | Clip |
| 87 | Tin | Gold flash |
| 83 | Tin | Gold 0.75 µm |

Replace NNN with the number of poles and XX-XXX with body size and layout numbers as indicated here. For example a 17x17 pin configuration with window and 168 contacts as shown here becomes 510-83-168-17-101101. Options: please consult for availability.- PGA sockets with optional standoffs.- PGA sockets with solder tails, length 4.2 mm.- PGA sockets with low profile contacts and solder tails of 2.8 mm length.

TECHNICAL ASSISTANCE

GENERAL SPECIFICATIONS:

The values listed below are general specs applying for PRECI-DIP PGA, BGA and PLCC sockets. Please see individual catalog page for additional and product specific technical data.

| | |
|-----------------------------|---------------------------------|
| Operating temperature range | -55 ... +125 °C |
| Climatic category (IEC) | 55/125/21 |
| Operating humidity range | annual mean 75 % |
| Max working voltage | 100 VRMS/150 VDC (2.54 mm grid) |

PRECI-DIP sockets are recognized by Underwriters Laboratories Inc. and listed under "Connectors for Use in Data, Signal, Control and Power Applications", File Nr. E174442

MECHANICAL CHARACTERISTICS:

| | |
|-----------------------------------|---|
| Clip retention | Min. 40 N (no displacement under axial force applied) |
| Contact (sleeve / clip) retention | Min. 3.3 N acc. to MIL-DTL-83734, pt 4.6.4.2 |

ELECTRICAL CHARACTERISTICS:

| | |
|---|----------------------------|
| Insulation resistance between any two adjacent contacts | Min. 10'000 M at 500 V AC |
| Capacitance between any two adjacent contacts | Max. 1 pF (PLCC max. 2 pF) |
| Self inductance per contact | Max. 2 nH |

ENVIRONMENTAL CHARACTERISTICS:

The sockets withstand the following environmental tests without mechanical and electrical defects:

- Dry heat steady state IEC 60512-11-9.11i / 60068-2-2.Bb: 125 °C, 16h
- Damp heat cyclic IEC 60512-11-12.11m / 60068-2-30.Db: 25/55 °C, 90 – 100 %rH, 1 cycle of 24 h
- Cold steady state IEC 60512-11-10.11j / 60068-2-1.A: -55 °C, 2 h
- Thermal shock IEC 60512-11-4.11d / 60068-2-14.Na: -55/125 °C, 5 cycles 30 min
- Sinusoidal vibrations IEC 60512-6-4.6d / 60068-2-6.Fc: 10 to 500 Hz, 10 g, 1 octave/min, 10 cycles for each axis
- Shock IEC 60512-6-3.6c / 60068-2-27.Ea: 50 g, 11 ms, 3 shocks in three axis

During the above two tests no contact interruption >50 ns does appear.

- Solderability J-STD-002A, Test A, 245°C, 5 s solder alloy SnAg3.8Cu0.7
- Resistance to soldering heat J-STD-0020C, 260°C, 20 s
- Moisture sensitivity J-STD-020C level 1
- Resistance to corrosion :
 - 1) Salt spray test IEC 60068-2-11.Ka: 48 h
 - 2) Sulfur dioxide (SO₂) test IEC 60068-2-42 Kc: 96 h at 25 ppm SO₂, 25 °C, 75 %rH
 - 3) Hydrogen sulfide (H₂S) test IEC 60068-2-43 Kd: 96 h at 12 ppm H₂S, 25 °C, 75 %rH

SOLDERLESS COMPLIANT PRESS-FIT CHARACTERISTICS:

PRESS-FIT CHARACTERISTICS MEASURED ACC. TO IEC 60352-5

- Press-in force: 90 N max. (at min. hole dia.) / 65 N typ.
- Push-out force: 30 N min. (at max. hole dia.) / 50 N typ.
- Push-out 3rd cycle: 20 N min. (at max. hole dia.)

PCB HOLE DIMENSIONS

- 2.54 mm grid: Finished hole Ø: 1 + 0.09/-0.06 mm | Drilled hole Ø: 1.15 ± 0.02 mm

- Interstitial grid: Finished hole \varnothing : $0.7 + 0.09/-0.06$ mm | Drilled hole \varnothing : 0.8 ± 0.02 mm

PCB HOLE PLATING

- PCB surface finish: Hole plating
- Tin: 5-15 μm tin over min. 25 μm copper
- Copper: min. 25 μm copper
- Gold over nickel: 0.05-0.2 μm gold over 2.5-5 μm nickel over min. 25 μm copper